



Handbook of 3D Integration, Volume 3: 3D Process Technology

From Wiley-VCH



Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH

Edited by key figures in 3D integration and written by top authors from high-tech companies and renowned research institutions, this book covers the intricate details of 3D process technology. As such, the main focus is on silicon via formation, bonding and debonding, thinning, via reveal and backside processing, both from a technological and a materials science perspective. The last part of the book is concerned with assessing and enhancing the reliability of the 3D integrated devices, which is a prerequisite for the large-scale implementation of this emerging technology.

Invaluable reading for materials scientists, semiconductor physicists, and those working in the semiconductor industry, as well as IT and electrical engineers.

<u>Download Handbook of 3D Integration, Volume 3: 3D Process T ...pdf</u>

Read Online Handbook of 3D Integration, Volume 3: 3D Process ...pdf

Handbook of 3D Integration, Volume 3: 3D Process Technology

From Wiley-VCH

Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH

Edited by key figures in 3D integration and written by top authors from high-tech companies and renowned research institutions, this book covers the intricate details of 3D process technology. As such, the main focus is on silicon via formation, bonding and debonding, thinning, via reveal and backside processing, both from a technological and a materials science perspective. The last part of the book is concerned with assessing and enhancing the reliability of the 3D integrated devices, which is a prerequisite for the large-scale implementation of this emerging technology.

Invaluable reading for materials scientists, semiconductor physicists, and those working in the semiconductor industry, as well as IT and electrical engineers.

Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH Bibliography

- Sales Rank: #2336340 in Books
- Published on: 2014-07-21
- Original language: English
- Number of items: 1
- Dimensions: 9.90" h x 1.10" w x 6.90" l, .0 pounds
- Binding: Hardcover
- 474 pages

Download Handbook of 3D Integration, Volume 3: 3D Process T ...pdf

<u>Read Online Handbook of 3D Integration, Volume 3: 3D Process ...pdf</u>

Editorial Review

From the Back Cover

Edited by key figures in 3D integration and written by top authors from high-tech companies and renowned research institutions, this book covers the intricate details of 3D process technology.

As such, the main focus is on silicon via formation, bonding and debonding, thinning, via reveal and backside processing, both from a technological and a materials science perspective. The last part of the book is concerned with assessing and enhancing the reliability of the 3D integrated devices, which is a prerequisite for the large-scale implementation of this emerging technology.

Invaluable reading for materials scientists, semiconductor physicists, and those working in the semiconductor industry, as well as IT and electrical engineers.

About the Author

Philip Garrou is a consultant and expert witness in the field of IC packaging materials and applications, prior to which he was Dir. of Technology and Business Dev. for Dow Chemicals' Electronic Materials business. Dr. Garrou is a Fellow of IEEE and IMAPS and served as President of the IEEE CPMT Society and IMAPS. He has co-authored 3 microelectronics texts and 100+ publications. He is Assoc. Ed. and author of the weekly blog "Insights from the Leading Edge" for Solid State Technology and has co-authored 3DIC reports for both TechSearch and Yole.

Mitsumasa Koyanagi is Professor in the Graduate School of Engineering at Tohoku University, Japan. After his PhD in electrical engineering he joined the Central Research Laboratory of Hitachi where he was engaged in the research on semiconductor memories. After a three-year stay at the Xerox Palo Alto Research Center in California, USA, he became Professor in the Research Center for Integrated Systems at Hiroshima University, Japan. Mitsumasa Koyanagi received numerous awards, including the Solid-State Devices and Materials Award.

Peter Ramm is head of the department Heterogeneous System Integration of Fraunhofer EMFT in Munich, Germany, where he is responsible for the key competence "Si Processes, Device and 3D Integration". He received the physics and Dr. rer. nat. degrees from the University of Regensburg and subsequently worked for Siemens in the DRAM facility where he was responsible for the process integration. In 1988 he joined Fraunhofer IFT in Munich, focusing for more than 25 years on 3D integration technologies. Peter Ramm is co-author of over 100 publications and 24 patents and editor of Wiley's "Handbook of Wafer Bonding". He received the "Ashman Award 2009" from IMAPS "For Pioneering Work on 3D IC Stacking and Integration".

Users Review

From reader reviews:

Katherine Sherrer:

Do you have favorite book? Should you have, what is your favorite's book? E-book is very important thing for us to learn everything in the world. Each reserve has different aim as well as goal; it means that publication has different type. Some people really feel enjoy to spend their time and energy to read a book. They are really reading whatever they have because their hobby is usually reading a book. What about the

person who don't like studying a book? Sometime, individual feel need book when they found difficult problem or exercise. Well, probably you should have this Handbook of 3D Integration, Volume 3: 3D Process Technology.

Michael Milliner:

Book is definitely written, printed, or illustrated for everything. You can know everything you want by a book. Book has a different type. As you may know that book is important issue to bring us around the world. Alongside that you can your reading expertise was fluently. A publication Handbook of 3D Integration, Volume 3: 3D Process Technology will make you to become smarter. You can feel far more confidence if you can know about everything. But some of you think that open or reading a new book make you bored. It is far from make you fun. Why they can be thought like that? Have you trying to find best book or acceptable book with you?

Tonya Sewell:

The particular book Handbook of 3D Integration, Volume 3: 3D Process Technology will bring that you the new experience of reading a new book. The author style to spell out the idea is very unique. In the event you try to find new book you just read, this book very acceptable to you. The book Handbook of 3D Integration, Volume 3: 3D Process Technology is much recommended to you to study. You can also get the e-book in the official web site, so you can quicker to read the book.

Alfred Leahy:

Reading a reserve tends to be new life style in this era globalization. With reading through you can get a lot of information that could give you benefit in your life. Together with book everyone in this world can share their idea. Publications can also inspire a lot of people. Plenty of author can inspire all their reader with their story or their experience. Not only the storyline that share in the textbooks. But also they write about the knowledge about something that you need example of this. How to get the good score toefl, or how to teach your children, there are many kinds of book which exist now. The authors nowadays always try to improve their talent in writing, they also doing some research before they write with their book. One of them is this Handbook of 3D Integration, Volume 3: 3D Process Technology.

Download and Read Online Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH #1S5U64OMXIC

Read Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH for online ebook

Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH Free PDF d0wnl0ad, audio books, books to read, good books to read, cheap books, good books, online books, books online, book reviews epub, read books online, books to read online, online library, greatbooks to read, PDF best books to read, top books to read Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH books to read online.

Online Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH ebook PDF download

Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH Doc

Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH Mobipocket

Handbook of 3D Integration, Volume 3: 3D Process Technology From Wiley-VCH EPub